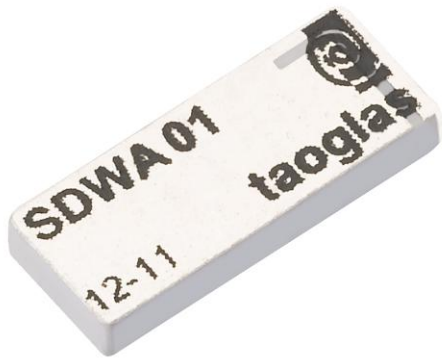


## Specification

Model No.	:	SDWA.01
Part No.	:	<b>SDWA.01</b>
Product Name	:	Dual-Band 2.4/5GHz Wi-Fi Ceramic SMD Antenna 2400MHz to 2500MHz 4900MHz to 6000MHz
Features	:	High Efficiency/ High Peak Gain Low Profile 10*4*1.5mm <b>RoHS</b> ✓

Photo



## 1. Introduction

The SDWA.01 dual-band SMT ceramic antenna is an embedded high efficiency, high peak gain solution for Wi-Fi 802.11n and other ISM band applications which require high data speed rates and wide coverage areas. It is designed to perform optimally mounted in the corner of a device main-board. Two SDWA.01 antennas can be used for optimal performance for MIMO applications. Its low profile allows use on extremely thin devices while still maintaining highest RF performance characteristics. All that is needed is a 50 Ohm co-planar waveguide (CPW) to the module.

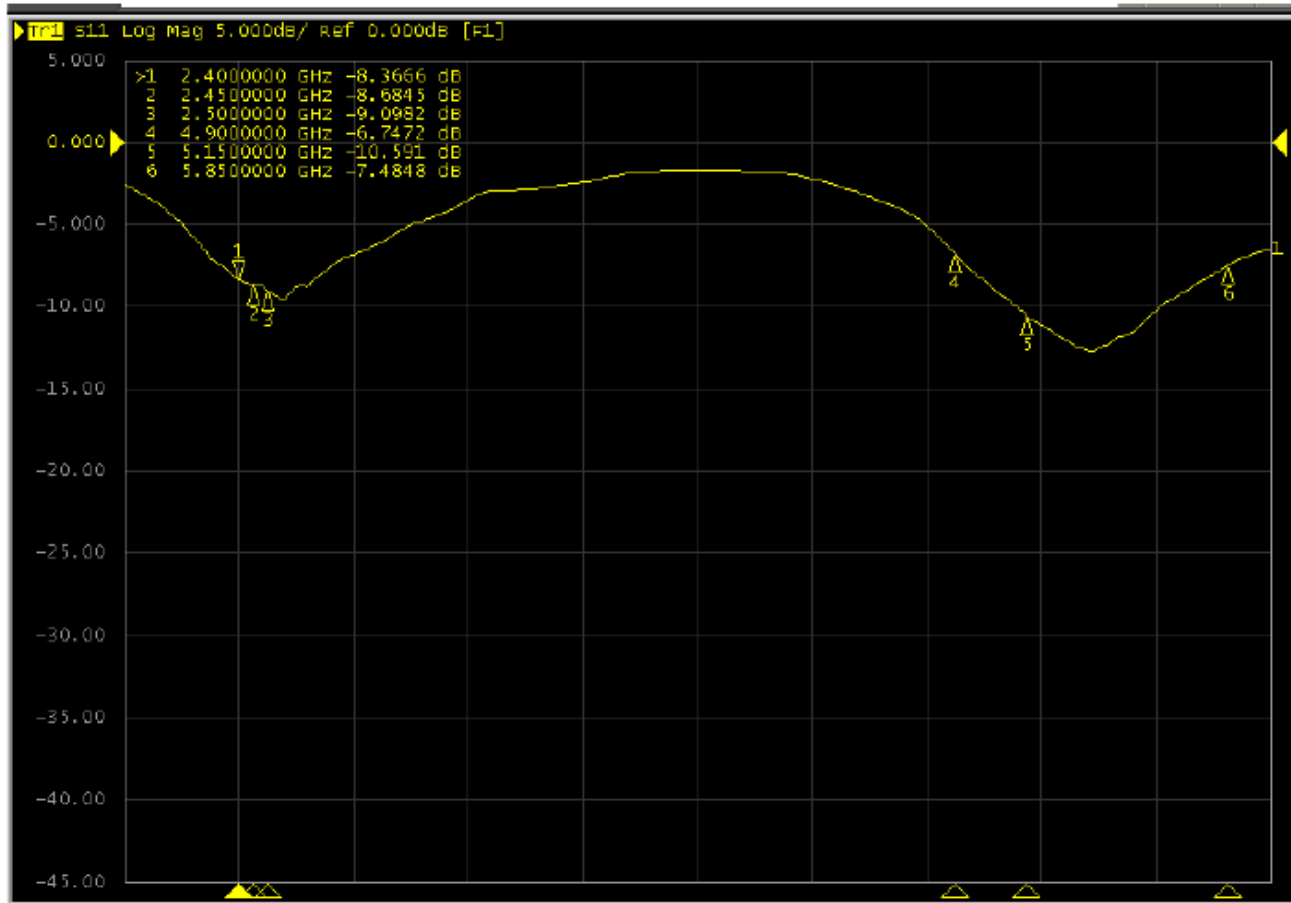
## 2.0 Electrical Characteristics

No	Parameter	Specification	
1	Working Frequency	2400~2500MHz 4900~5850MHz	
2	Dimension	10*4*1.5mm	
3	Impedance	50 Ohm	
4	VSWR	2.5 max.	2450~2500MHz
		3.0 max.	4900~5850MHz
5	Polarization	Linear	
6	Termination	Ag(Environmentally-Friendly Pb Free)	
7	Operating Temperature	-40°C to +85°C	

\*These values are based on our standard 100mm\*50mm test board. Actual electrical values will change depending on ground plane size, shape, mounting position, matching circuit design and surrounding environment.

### 3.0 Key Antenna Performance Indicators

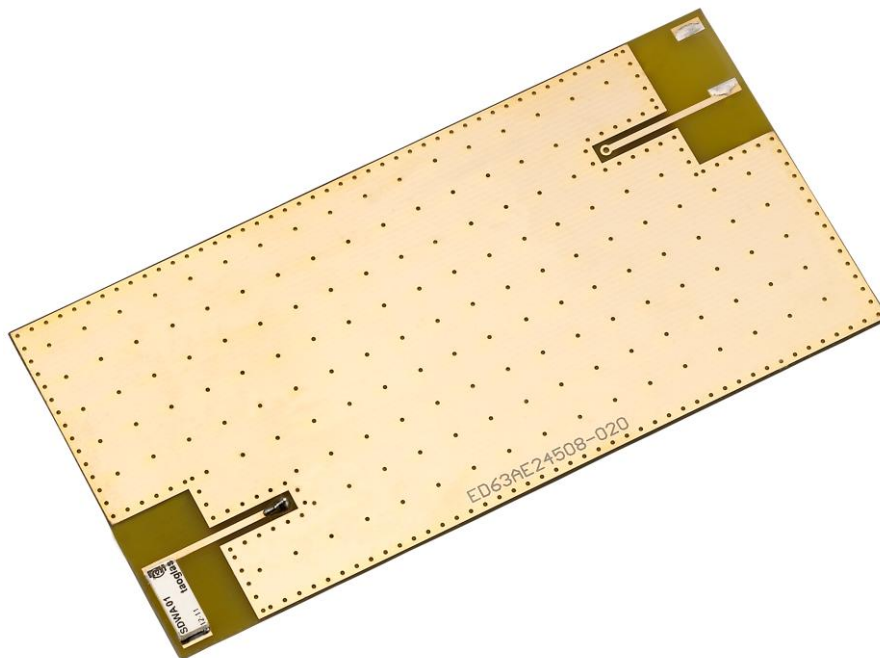
#### 3.1 S11 Response Curve



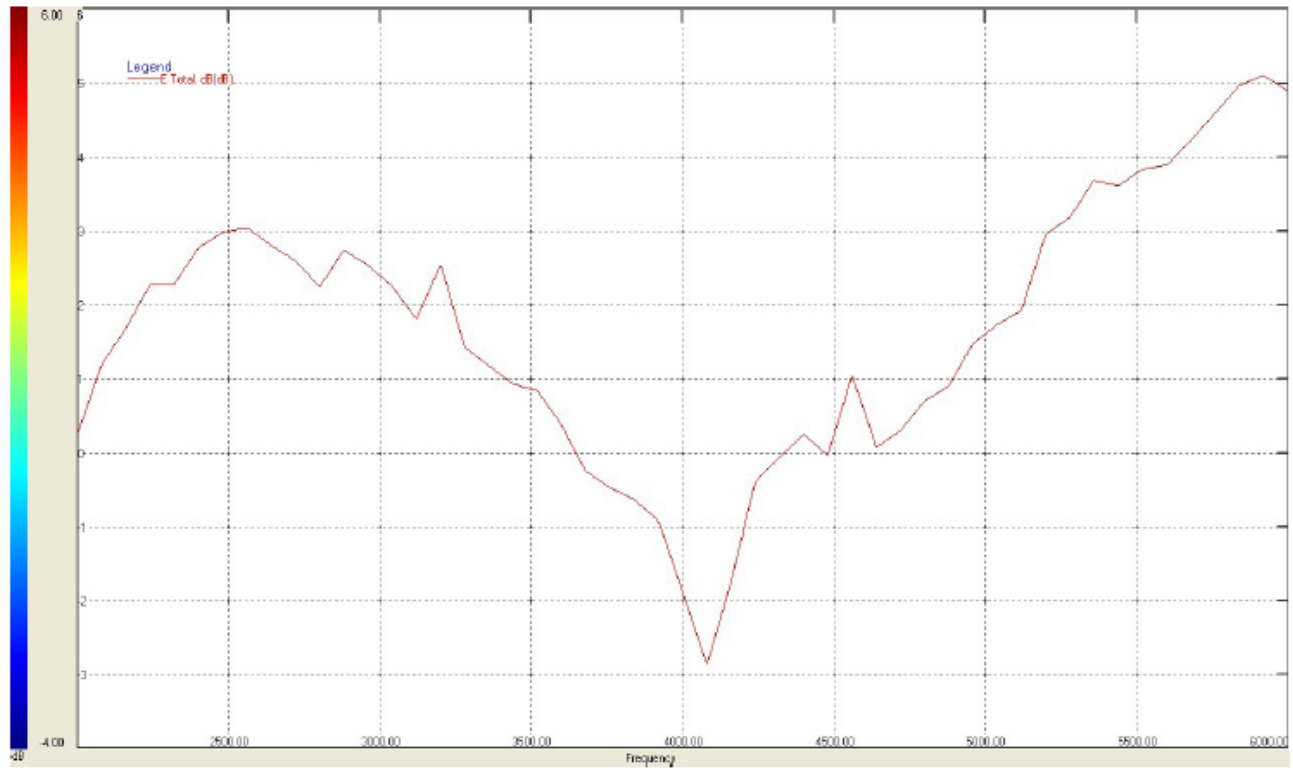
### 3.2 Efficiency & Gain

Frequency(MHz)	Wi-Fi(MHz) (free space)					
	2400	2450	2500	4900	5150	5825
Peak Gain (dBi)	2.78	2.91	3	1.05	2.32	4.91
Average Gain (dBi)	-1.7	-1.64	-1.6	-2.13	-1.25	-1.74
Efficiency (%)	67.48	68.42	69.11	61.36	74.95	66.89

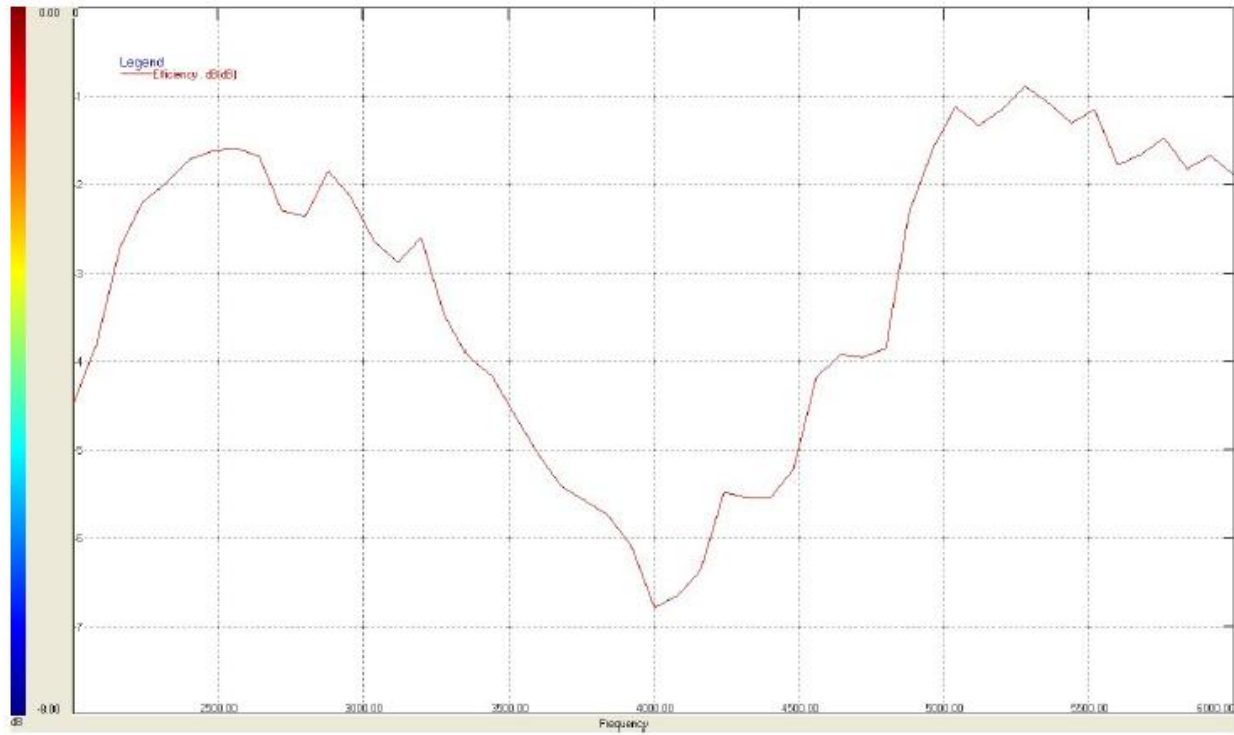
Based on standard evaluation board.



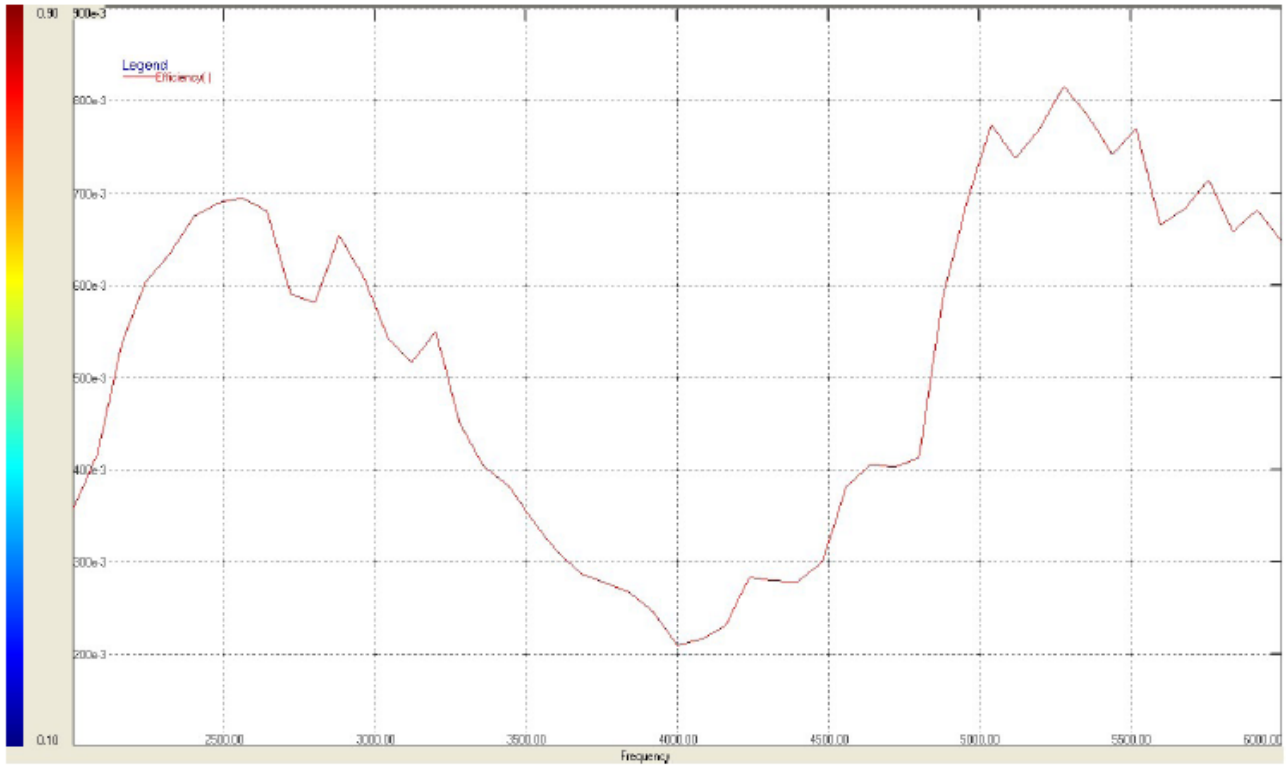
### Peak Gain



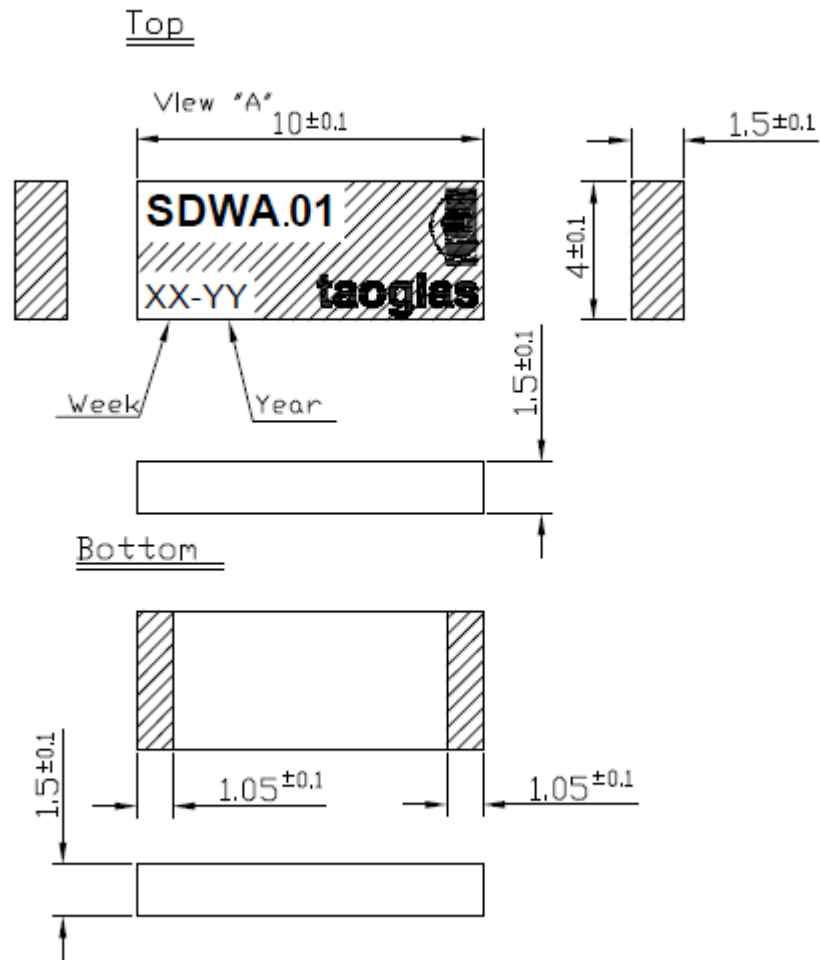
### Average Gain



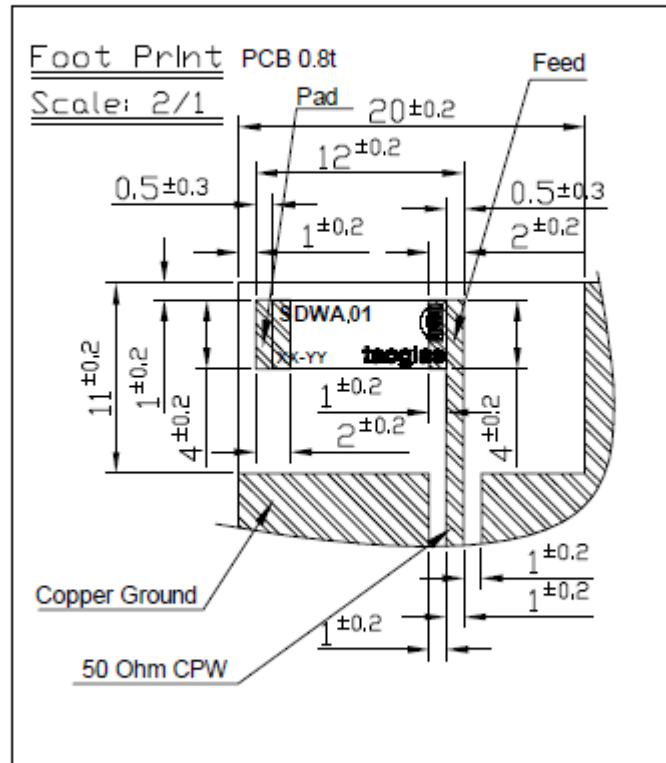
## Efficiency



## 4.0 Drawings and Dimensions

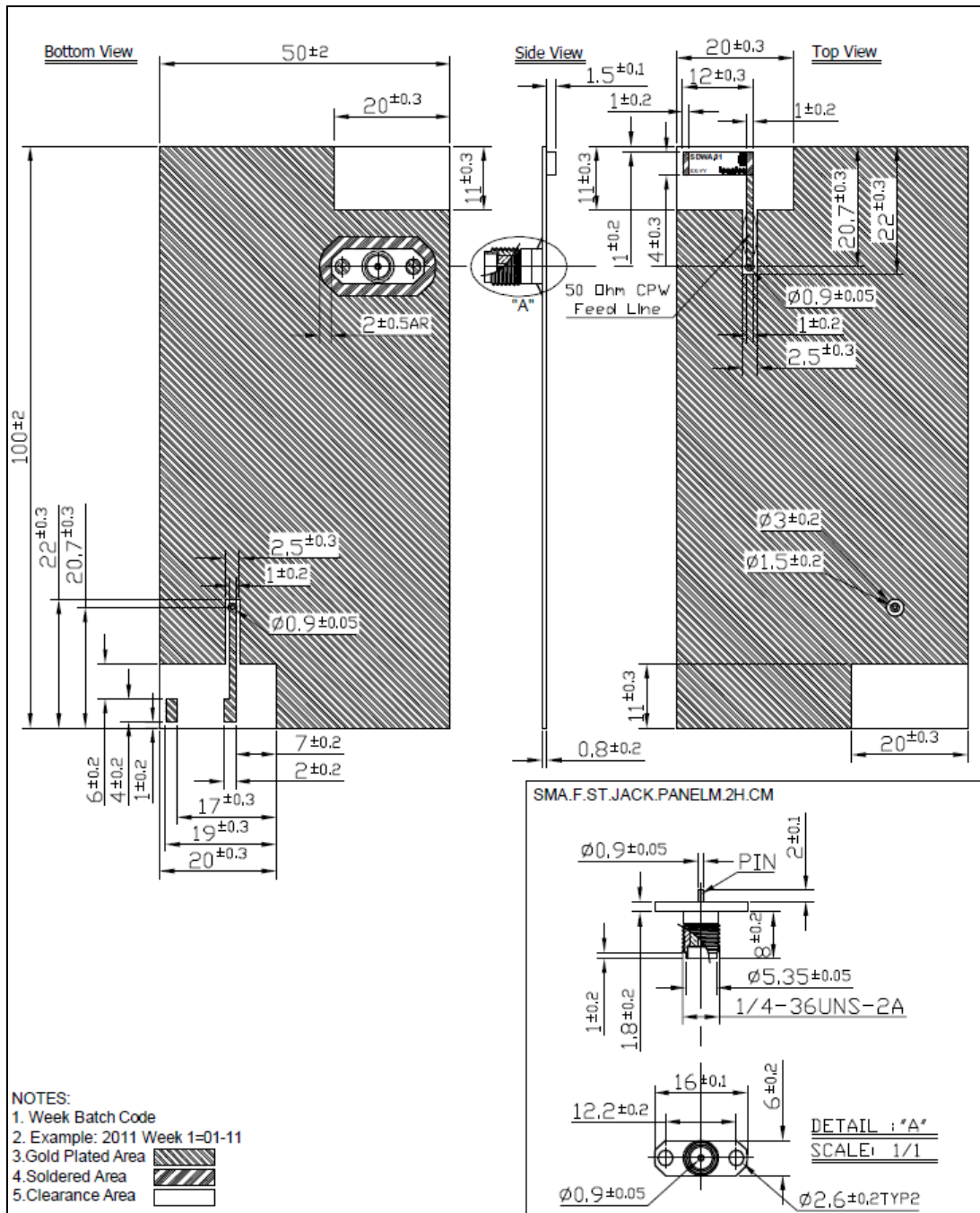






## 5.0 Test Board Dimensions

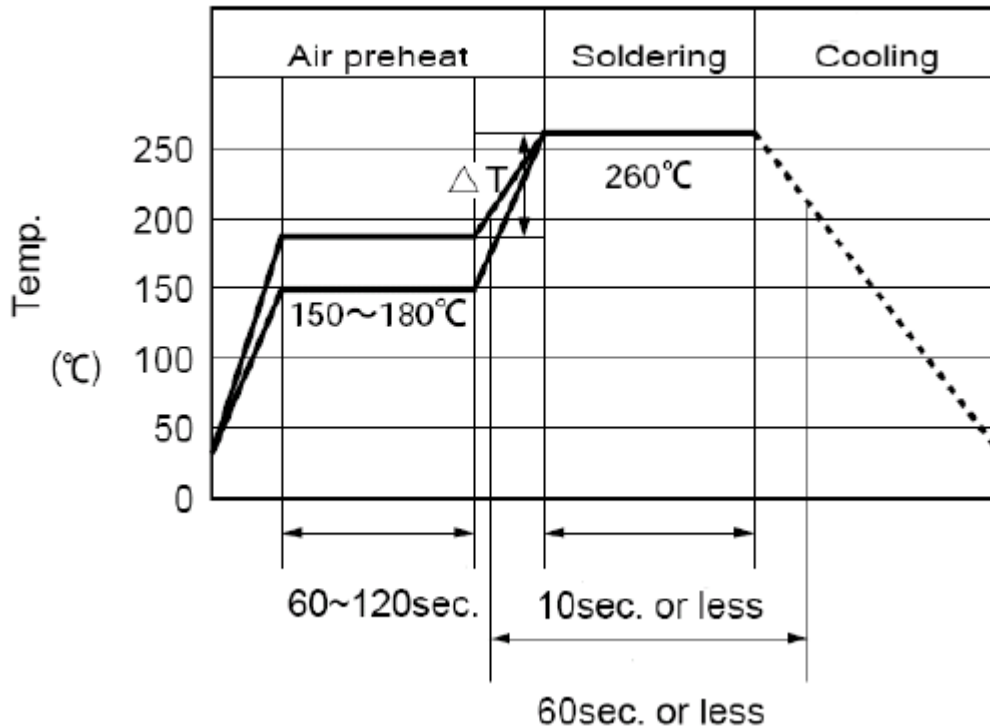
The test Board is designed for evaluation purposes.



The size of the ground plane for the complete evaluation board is 100x50 mm. The area occupied by the antenna is 20x11 mm.

## 6.0 Recommended Soldering Conditions

Lead free Solder



1. Time shown in the above figures is measured from the point when chip surface reaches temperature.
2. Temperature difference in high temperature part should be within 110°C.
3. After soldering, do not force cool, allow the parts to cool gradually.

\*General attention to soldering:

- High soldering temperatures and long soldering times can cause leaching of the termination, decrease in adherence strength, and the change of characteristic may occur.
- For soldering, please refer to the soldering curves above. However, please keep exposure to temperatures exceeding 200°C to under 50 seconds.
- Please use a mild flux (containing less than 0.2wt% Cl). Also, if the flux is water soluble, be sure to wash thoroughly to remove any residue from the underside of components that could affect resistance.

### Cleaning:

When using ultrasonic cleaning, the board may resonate if the output power is too high. Since this vibration can cause cracking or a decrease in the adherence of the termination, we recommend that you use the conditions below.

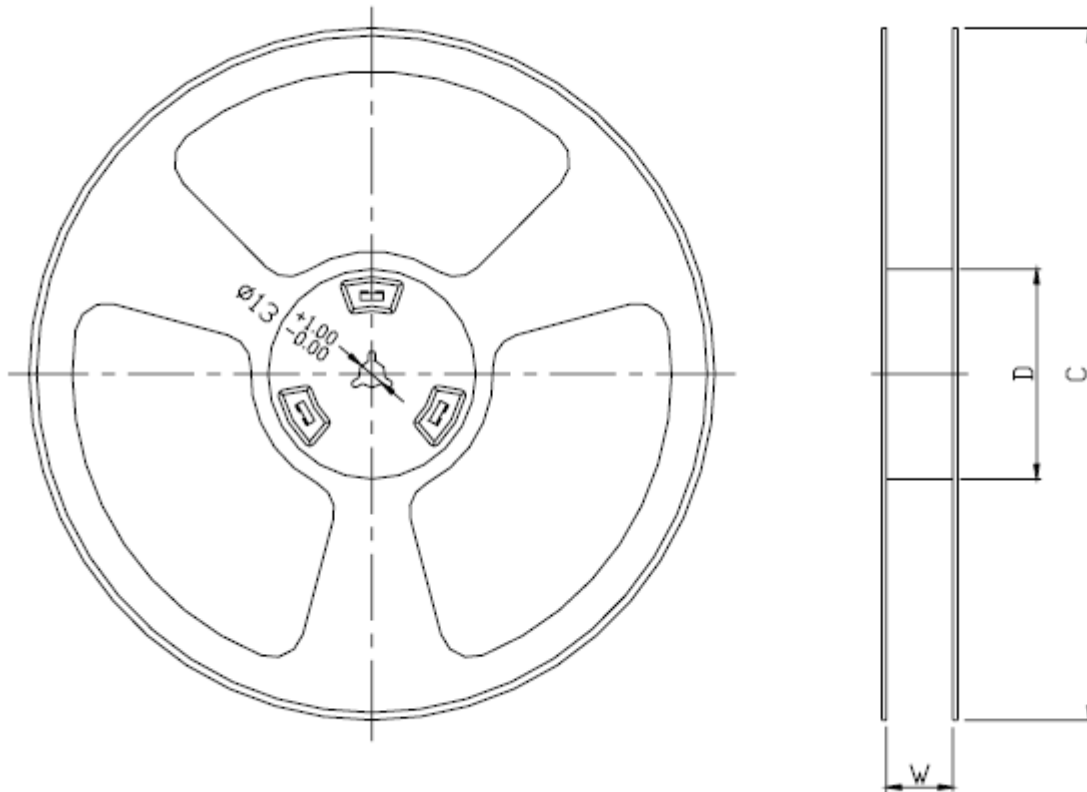
Frequency: 40 kHz max.

Output power: 20W/liter

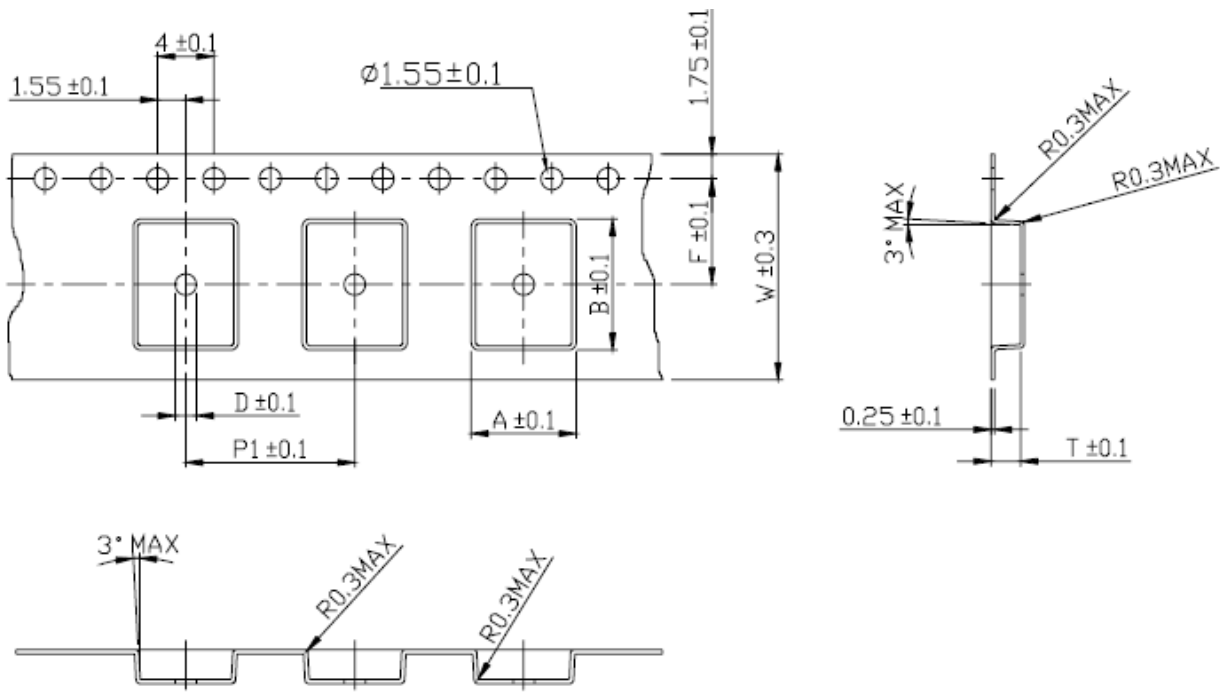
Cleaning time: 5minutes max.

## 7.0 Delivery Mode

1. Blister tape to IEC 286-3 , polyester ◦
2. Pieces/tape: 1500



Product Code	Units per Reel	C(mm)	D(mm)	W(mm)
Antenna	1500	330±1	100±0.5	24±1



No	Index	Spec(mm)
1	A	4.6
2	B	10.6
3	P1	12
4	W	24
5	F	8.5
6	T	2.5
7	D	1.5